

# **Product Data Sheet**

#### **T-5A**

Inorganic Hot Tinning Water Soluble Liquid Flux

## ROHS compliant

## **Product Description**

T-5A is an inorganic acid flux. It is very active flux of zinc-ammonium type. T-5A is a fumeless and non-flammable aqueous solution designed to restore the solderability of tarnished copper surface especially for hot solder tinning process for copper wire operations. The flux residue can be completely removed with thorough water rinse providing copper wire surface free from ionic contamination.

### Application

The copper wire is first applied through the flux pot which contains T-5A. After fluxing, no preheating is required and the surface of the copper wire is cleaned by passing the wire through a wet cloth before wire is conveyed through the bath of molten solder. T-5A can be used as received or diluted 1:1 with water in plastic containers at room temperature.

#### Residue Removal

The residue left after soldering is hygroscopic and ionisable. Complete residue removal immediately after soldering is recommended. Removal of the residue can best be achieved with water at a minimum temperature of 40°C, followed by a final deionised water rinse.

#### **Recommended Solvent**

No solvent is required.

### **Health and Safety**

Observe standard precautions for handling and use, such as well-ventilated areas and avoidance of prolonged or repeated contact with the skin. For more information, please refer to the Material Safety Data Sheet.

### **Storage**

Under proper storage condition, T-5A can be stored for about 6 months.

### **Packaging**

Available in 25kg/carboy.

DISCLAIMER OF LIABILITY

## Specification

Item	Result
State	Liquid
Colour	Colourless
Specific Gravity	1.02 +/- 0.005
@ 25°C	
JIS Z 3197 8.2.2	
Non-volatile Solid	2.1 +/- 0.3 wt%
Content (110°C, 3hr)	
IPC-TM-650 2.3.34	
JIS Z 3197 8.1.3	
Halide Content	1.9 +/- 0.1 wt%
JIS Z 3197 8.1.4.2.1	
Water Extract	$> 1 \times 10^4 \Omega$ -cm
Resistivity	
JIS Z 3197 8.1.1	
Copper Corrosion Test	Pass
IPC-TM-650 2.6.15	
JIS Z 3197 8.4.1	
рН	2
Flash Point	None
Spread Factor	> 85% (SnPb)
JIS Z 3197 8.3.1.1	> 80% (SnCu3 and SnAg3.5)
Surface Finish	Shiny

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